Adhesive dosing, mixing and application units

for the production of sandwich elements
## Applications

<table>
<thead>
<tr>
<th>Composite panel</th>
<th>Core material</th>
<th>Covering</th>
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<tbody>
<tr>
<td></td>
<td>rigid foam</td>
<td>Aluminium</td>
</tr>
<tr>
<td></td>
<td>honey comb</td>
<td>Sheet steel</td>
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<tr>
<td></td>
<td>construct</td>
<td>GRP</td>
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<tr>
<td></td>
<td>wood</td>
<td>Rigid-PVC</td>
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<td></td>
<td></td>
<td>Plywood</td>
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<td></td>
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<td>HPL, CPL, HDF</td>
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<table>
<thead>
<tr>
<th>Building panel</th>
<th>Core material</th>
<th>Covering</th>
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<tbody>
<tr>
<td></td>
<td>XPS/EPS foam</td>
<td>Aluminium</td>
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<tr>
<td></td>
<td>PUR/PIR foam</td>
<td>GRP</td>
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<tr>
<td></td>
<td></td>
<td>Rigid-PVC</td>
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<table>
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<th>Insulation panel</th>
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<tbody>
<tr>
<td></td>
<td>XPS/EPS foam</td>
<td>Aluminium</td>
</tr>
<tr>
<td></td>
<td>PUR/PIR foam</td>
<td>Chipboard</td>
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<tr>
<td></td>
<td>Stone wool</td>
<td>OSB</td>
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<td></td>
<td>Glass wool</td>
<td>MDF</td>
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<td></td>
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<td>Plywood</td>
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<tr>
<td></td>
<td></td>
<td>gypsum plaster board</td>
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<tr>
<td></td>
<td></td>
<td>gypsum fibre board</td>
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</tbody>
</table>
Surface application for 1C adhesive systems
Series OA 100

Value and advantages:

- Approved and reliable technology, owing to experience of many years in the adhesive dosage and application technology
- High production security by different monitoring devices along the entire dosing process
Customised solutions with Oest systems

**Areas of application:**
Application system for processing 1C-PUR adhesives for surface applications. For application width up to 3,500 mm and feeding speeds from 10–90 m/min.

**Technical Features:**
- Flexible connection to adhesive container or drum with silicagel filter
- Control receptacle with supply monitoring as intermediate buffer
- Consumption counter with warning limit to ensure adhesive container changes in time
- Frequency regulated dosing pumps for precise dosing of adhesive
- Switch point control of adhesive valves through position measuring system and/or sensors
- Pressure monitoring in the dosing lines
- Different application heads, according to the type of production and desired degree of automation
- Self-developed, reliable adhesive valves for the application heads
- Switch cabinet and operator panel according to VDE-Standard

**Accessories:**
- Material supply systems for flexible set-up of the adhesive containers
- Integrated remote maintenance systems
- Networking via bus systems with other controls and host computers
- CAD connection
- Adhesive heating in the dosing line for improving flow capacity at lower temperatures
- Monitoring camera for adhesive application
- Water spray systems to increase the reactivity of the PUR adhesive
- Mechanisations

- Low cleaning effort, by engineered design of the adhesive application heads
- Savings of adhesive and cleaning costs, due to accurate and controllable adhesive application
- Optimal adhesive distribution at minimum application quantity, by adhesive application in parallel threads
- Automatic control of the dosing quantity via adjustable parameters like application quantity, spreading width and feeding speed
Surface application for 2C adhesive systems
Series OM 100

Areas of application:
Dosing-, mixing and application unit for processing 2C-PUR adhesives for surface applications.
Systems for manual draw of mixed adhesive, for semi-automatic hand application, as well as for fully automatic application are available.

Technical Features:
- Flexible connection to adhesive container or drum with silicagel filter
- Control receptacle with supply monitoring as intermediate buffer
- Consumption counter with warning limit to ensure adhesive container changes in time
- Self-developed high pressure metering pumps for accurate adhesive dosage
- Pressure monitoring in the dosing lines
- Mixing of the components with static-mixer
- Easy to clean extruder heads
- Switch cabinet and operator panel according to VDE-Standard

Accessories:
- Material supply systems for flexible set-up of the adhesive and hardener container
- Integrated remote maintenance systems
- Networking via bus systems with other controls and host computers
- CAD connection possible
- Adhesive heating in the dosing line for improving flow capacity at lower temperatures
- Monitoring camera for adhesive application
- Mechanisations

Value and advantages:
- Approved and reliable technology, owing to experience of many years in the adhesive dosage and application technology
- High production security by different monitoring devices along the entire dosing process
Perfectly connected

- Low cleaning effort, by engineered design of the adhesive application heads
- Savings of adhesive and cleaning costs, due to accurate and controllable adhesive application
- Optimal adhesive distribution at minimum application quantity, by adhesive application in parallel threads
- Automatic control of the dosing quantity via adjustable parameters like application quantity, spreading width and feeding speed
Mechanisations

**Static portal**
- The work-piece moves underneath the static portal
- For 1C-PUR Systems
- For work-piece width up to 3,500 mm
- Movement speed 10–90 m/min.

**Traveling floor-portal**
- The application head moves over the static work-piece
- For 1C-PUR Systems
- For work-piece width up to 3,500 mm
- Movement speed 10–90 m/min.

**Traveling ceiling-portal**
- The application head moves over the static work-piece
- For 1C-PUR Systems
- For work-piece width up to 3,500 mm
- Movement speed 10–90 m/min.

**Outlining portal**
- The application head moves meandering over the static workpiece
- For 1C- and 2C-PUR Systems
- For work-piece width up to 3,500 mm
- Movement speed 10–40 m/min.